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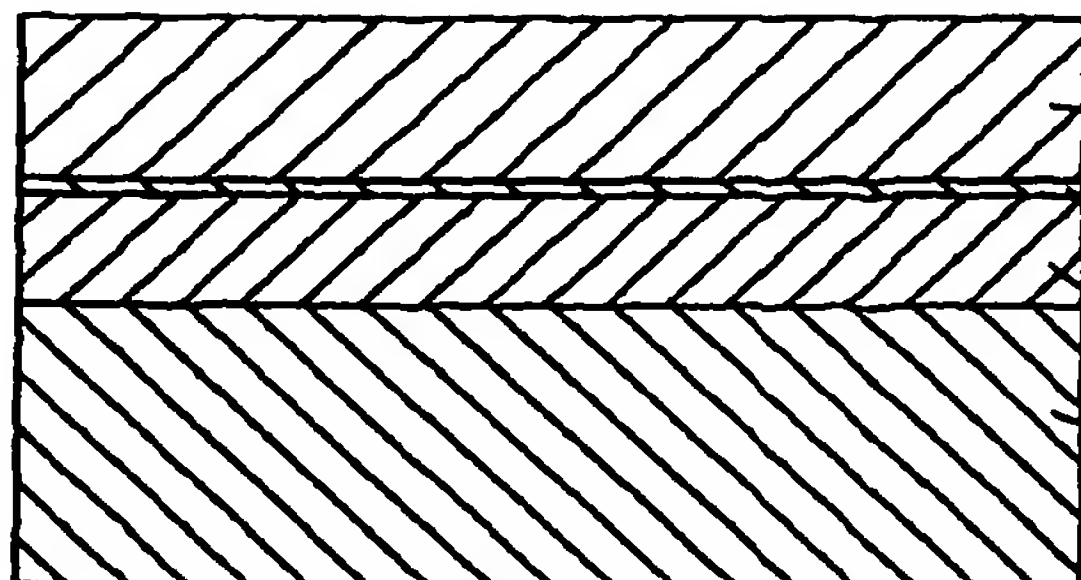
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(54) Title: ELECTRONIC PACKAGING MATERIALS FOR USE WITH LOW-K DIELECTRIC-CONTAINING SEMICONDUCTOR DEVICES



Silicon Die~0.73mm

Black Diamond ILD Structure~0.008mm

Underfill~0.05mm

Substrate~1.0mm

(57) Abstract: Electronic packaging materials for use with Low-k dielectric-containing semiconductor devices are provided.

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